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(71) Applicant (for all designated States except US): **SYS-
TEMS ON SILICON MANUFACTURING CO. PTE.
LTD.** [SG/SG]; 70 Pasir Ris Drive 1, Singapore 519527
(SG).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **KOH MENG
FEI** [MY/SG]; Blk 3, Dover Road, #07-354, Singapore
130003 (SG). **POH CHOON SIONG** [SG/SG]; blk 360C,

Admiralty Road, #12-36, Singapore 753360 (SG). **NEO
TECK LEONG** [MY/SG]; Blk 104, Woodlands Street 13,
#13-210, Singapore 730104 (SG). **LEONG THENG WEI**
[SG/SG]; Blk 483, Pasir Ris Drive 4, #11-477, Singapore
510483 (SG). **WANG, Bing** [CH/SG]; Blk 9, Elias Green,
#02-03, Singapore 519963 (SG).

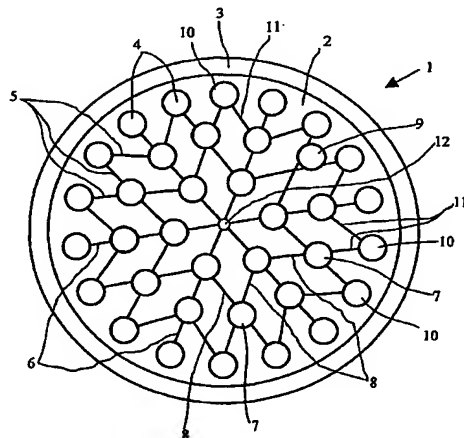
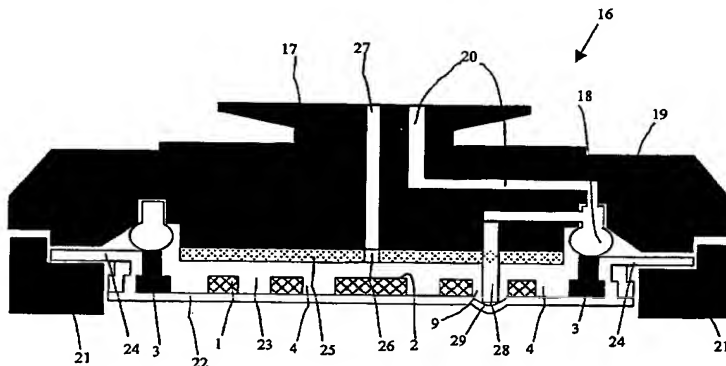
(74) Agent: **DREW & NAPIER LLC**; 20 Raffles Place,
#17-00, Ocean Towers, Singapore 048620 (SG).

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(54) Title: PERFORATED PLATE FOR WAFER CHUCK



(57) Abstract: A perforated plate (1) for use in a wafer-handling chuck (16) has a pattern of through holes (4) by which a vacuum is applied to a membrane (22) to form suction cups (31) that secure a wafer (30) to the chuck. Grooves (5) in a generally planar upper surface (2) of the plate interconnect the through holes. The grooves ensure the maintenance of the vacuum, and the consequent formation of the membrane suction cups, at each through hole, even when the grooved surface of the plate is in close face-to-face contact with another planar surface in the chuck. In one embodiment, the through holes in the perforated plate lie on concentric circles and the grooves interconnect radially-outward through holes to the next closest one or pair of radially-inward through holes.

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